

CALL FOR PAPERS

The Leading International Components, Packaging, and Manufacturing Technology Symposium

10th IEEE CPMT Symposium Japan

ICSJ2020 abstract submission deadline has been extended until June 30 2020.

November 9 – 11, 2020,

Kyoto Univ. Clock Tower Centennial Hall, Kyoto, JAPAN

<https://www.ieee-csj.org/>

“Electronics Packaging for 5G and B5G”

“IEEE CPMT Symposium Japan (ICSJ)” is one of the most widely recognized international conferences sponsored by the **IEEE Electronics Packaging Society (EPS)** and has been held annually in Kyoto in November. The conference originally started in 1992 as “The VLSI Packaging Workshop in Japan (VPWJ)” and was renamed to “ICSJ” in 2010. ICSJ provides a platform for you to communicate and interact with global leaders in packaging technology. ICSJ2020 is the commemorative event for 10th ICSJ and 19th conference since establishing VPWJ.

Electronics Packaging for 5G and B5G: The 5G commercial services have just began and provide higher transmission rate, lower latency, greater capacity of remote execution, and larger number of connected devices. The 5G advantages will dramatically advance the performance of IoT services, edge computing, virtual reality (VR), autonomous mobility, as well as artificial intelligence (AI). The future mobile network after 5G, which is called as “beyond 5G (B5G)”, already started technical discussions. The 5G and B5G services will realize Internet of Everything (IoE) services eventually. In 2020, our focus is on key electronics packaging technologies for next-generation mobile networks and their applications for *5G and B5G* services, and emphasizes on the following main topics: **Photonics, Advanced Packaging, Process & Material, Power & Automotive Electronics, Bioelectronics, and Sensing Technologies.** Additional topics of primary interest to the participants are listed below.

Other topics include (but not limited to):

- + 3D Packaging & Chip-on-Chip
- + Advanced Fine Pitch Packaging, Micro Bumping, CSP
- + Board-Level Integration & Integrated Substrate
- + Laminated Materials & Processing, Materials for Packaging
- + Reliability & Failure Mechanisms
- + Packaging for High-Speed Electrical Interconnect
- + Signal Integrity / Power Integrity
- + RF Components & Modules
- + Additive Manufacturing, 3D Printed Electronics
- + Brain-like Neuromorphic Chip Assembly
- + Resilient Packaging for Autonomous System
- + Low Power / Low Temperature / Ultra Low Noise System Packaging



This conference is a perfect opportunity for you to communicate, interact, exchange technical ideas, and discuss your latest novel research findings in 5G and B5G packaging technologies with experts from industry and academia. In addition to the regular sessions, there is an “Early Career Researchers’ (ECR)” poster session for young researchers with less than 2-year experience in their professions and all students including Ph.D. to hold fruitful communications with experts. Authors are invited to submit an abstract through our website <https://www.ieee-csj.org>. **The abstract deadline has been extended from May 22, 2020 to June 30, 2020.** Notification of acceptance will be sent by August 7, 2020, and the authors are requested to submit a 4-page manuscript by October 2, 2020 for the Technical Digest which will be available via **IEEE Xplore Digital Library**, whereas the authors for the ECR session are required to submit a 2-page manuscript.

Plenary & Special Speakers:

Ming Wu	(University of California, Berkeley)
Martin Shell	(Fraunhofer Heinrich Hertz Institute)
John H. Lau	(Unimicron Technology Corporation)
Chris Bailey	(University of Greenwich)
Sam Karikalan	(Broadcom Incorporated)
Robert Gee	(Continental)

Session Invited Speakers:

Nikolaos Bamiedakis	(University of Cambridge)	Ki-Hun Jeong	(KAIST)
Ignazio Piacentini	(ficonTEC Service GmbH)	Masahiro Horibe	(AIST)
Sven Otte	(Sicoya GmbH)	Toru Ujihara	(Nagoya University)
Agnes Tixier-Mita	(The University of Tokyo)	Katsuya Kikuchi	(AIST)

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Sponsor:

IEEE Electronics Packaging Society (EPS)

Cooperation:

IEEE EPS, Japan Chapter

Location:

Kyoto University Clock Tower Centennial Hall
Yoshidahonmachi, Sakyo-ku, Kyoto, 606-8501

